



ICB Transfer – Interface Products

Overview for transfers of the C100, C075 & C175 processes

As indicated in previous customer communications, NXP has informed customers of the impending closure of the ICB (Boblingen, Germany) diffusion facility. The intent of this document is to provide an overview of the planned activities with respect to the devices within the responsibility of the Interface Products affected by the closure. Although a small number of devices will be discontinued, the majority of the devices will be transferred to other Fabs with comparable processes. It should be noted that the IP group has already started the Qualification processes which will enable a successful and seamless transfer of the current production to other facilities. The excel spreadsheet accompanying this document provides a list of products, and a current status of the Interface Products' devices affected by the ICB closure.

Overall, the list can be broken down further into 3 groups: Devices with a suffix of /G, Devices to be discontinued (EOL) and Devices to be transferred.

Devices currently suffixed (or referred to) as /G devices;

Those devices currently available in the /G naming format, and on the list attached to this PCN, will, until Inventory is depleted, continue to be available using the ICB material. As devices with the /G ordering suffix are also available in the standard (non /G) ordering convention, the standard (non /G) version, unless otherwise specified, will be used as the recommended replacement vehicle.

Devices slated for discontinuation (EOL);

Those devices slated for discontinuation, will be noted in the spreadsheet as (EOL – Life Time buy) and as available, recommended replacement(s) are listed. Devices set for EOL, will be officially put-forth into the standard DN system as used by NXP.

Devices slated for transfer;

Those devices on the list which slated for transfer are indicated as such in the spreadsheet within the comment field. The Receiving Fab is indicated as such under the column headed as 'Receiving Fab'. Activities and an Estimate of timing with respect to Samples, Qualifications and Release dates are also included within individual columns. The Process column is available for sorting, and will be used to further differentiate future PCN's which, due to individual process Qualification requirements, will be used to report upcoming Qualifications. With respect to the individual; process indicators, the following comments should be noted;

For devices processed on C175:

The C175 process is currently run and used by PL-IP in TSMC. TSMC versions are drop in compatible, with devices (in many cases) already dual sourced. For parts not already dual sourced, validation of TSMC material will be subjected to, at a minimum, Characterization and ESD verification as well as validation to current Final Test Standards.

For devices processed on C075:

The C075 process is currently run and used by PL-IP in ICN8. ICN8 versions are drop in compatible, with devices (in several cases) already dual sourced. For parts not already dual sourced validation of ICN8 material will be performed at a minimum through device level Characterization and ESD verification as well as validation to current Final Test Standards.

For devices processed on C100:

The C100 process originated in ICN8. The current process is being validated against PL-IP requirements. To validate ICN8 material, PL-IP plans on a 3 lot Qualification, which will include Reliability Stressing, device level Characterization, ESD verification as well as validation to current Final Test Standards.

Parts listed as Development are expected to be initially released out of ICB, and then will transfer to the appropriate fab as listed in the Receiving Fab column. For Qualifications, follow-up PCN's based on the process/device type groupings will be sent to customers at a later date.

Business Line Standard IC's
Product Line Interface Products
Quality Engineering
Prepared by: David Bannon
Updated 06/18/2007



NXP Semiconductors
8375 S. River Parkway, Tempe, AZ
www.nxp.com

